

IN THE ABSTRACT:

Please REPLACE the Abstract in its entirety with the following:

A component-embedded board fabrication method includes detecting, before the board is covered with a first insulating layer, the actual position of a first electronic component formed on a surface of the board, calculating a displacement between the design position of the first electronic component on the surface of the board and holding the displacement as first displacement data, and correcting, based on the first displacement data, design data to be used for processing the board after the board is covered with the first insulating layer.